

Serial Nr.: 09/209,634
Art Unit: 2811

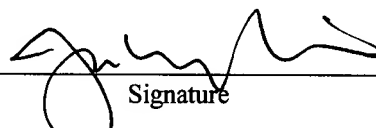
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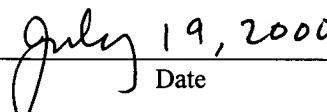
IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Serial No.: 09/209,634 Examiner: Luan Thai
Inventor: Fang-Jun Leu, Rong-Shen Lee, Hsin-Chien Huang,
Randy Hsiao-Yu Lo and Chiang-Han Day
Filed: December 10, 1998 Art Unit: 2811
Title: Flip-Chip Ball Grid Array Package With A Heat Slug

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Assistant Commissioner for Patents
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Sir:

AMENDMENT

In response to the Office Action mailed 05/03/2000, please amend the above-identified application as follows:

DRAWINGS:

FIG. 1 is designated by a legend --Prior Art-- as marked in red in the attached drawing.

SPECIFICATION:

Page 5, line 19, before "The good", insert the sentence, The hollow cylindrical structure
provides good support and protection for the semiconductor package to prevent it
from being damaged by an external force.

Page 5, line 20, change "assist" to --assists--.



#3/assn
Corr
Chen
7/27/00
enter phone
LT.

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JUL 27 2000
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